

Proton beam writing of buried channel waveguides in Foturan glass

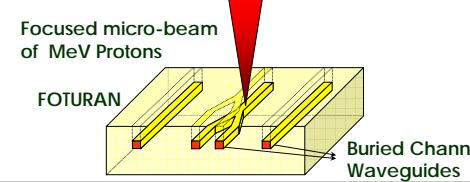
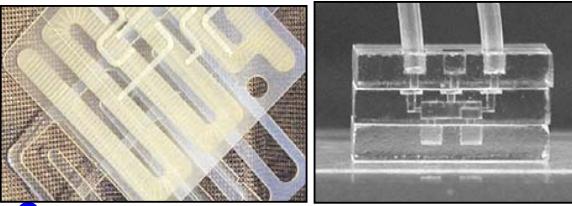
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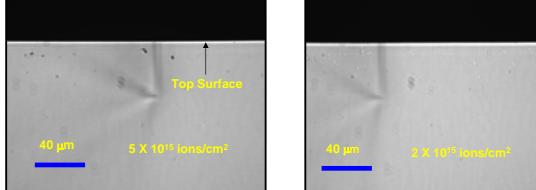
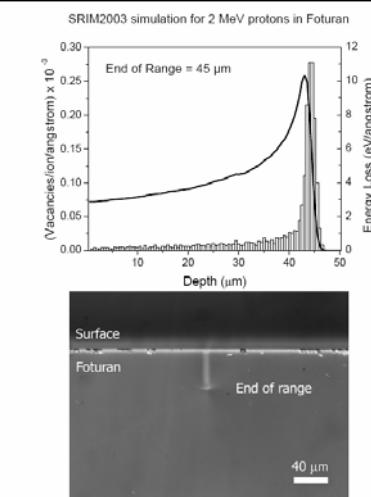
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Introduction

- ❖ Compatibility → Biomedical applications
- ❖ Combines unique glass properties (transparency, hardness, chemical and thermal resistance, etc.) and the prospect to achieve extremely fine structures with tight tolerances and High Aspect Ratio
- ❖ Structures <500 nm are now possible. With appropriate heat treatment and processing the resultant mass can be either etched away to provide a true 3-D structure or the resultant structure can be heat treated to become fully ceramicised.
- ❖ Applications include micro-fluidic manifolds, precise glass/ceramic diffraction gratings, integrated optical structures for Photonics.



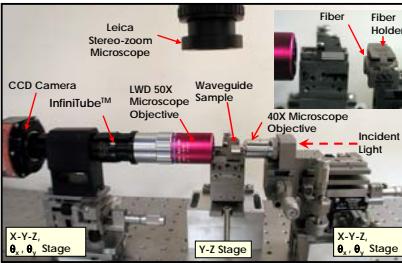
Fabrication



Proton Beam Writing

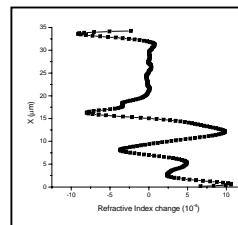
- Direct-write technique. Focused sub-micron beam of **high energy protons** for writing directly on suitable materials: PMMA, SU-8, Glasses, Polymers etc.
- **High Aspect Ratio** micro- and nano-structures with **straight and smooth sidewalls** (~3 nm roughness).
- Small lateral spread (except at the end of range) → Vertical walls.
- Well defined range: slots & channels with well defined depth.
- Different ion energies → Multi-layered structures.
- 3D capability with high aspect ratio structures > 160.
- 100 nm and below structures possible; 30 nm structures already demonstrated

Experimental Set Up

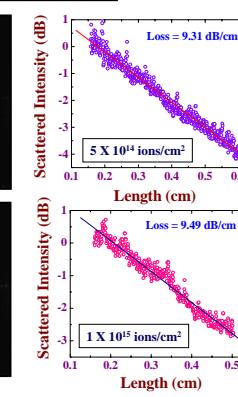


Characterization

Refractive Index Profile

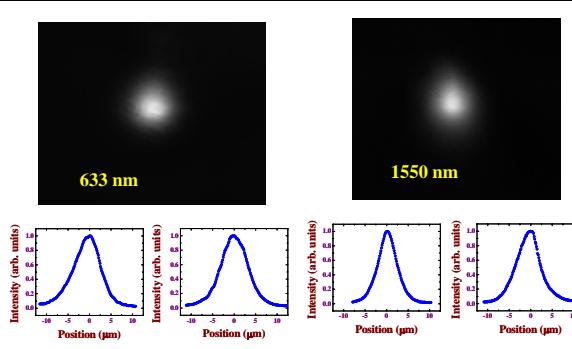


Loss Profiles



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Mode Profile @ 633 nm

